

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	8	(substrate or wafer or semiconductor or workpiece) same (bubb1\$3 or foam\$3) near3 (sens\$3 or detect\$3) near3 (multiple or plurality)	US-PGPUB; USPAT	OR	ON	2005/09/27 13:23
L8	8	(substrate or wafer or semiconductor or workpiece) same (bubb1\$3 or foam\$3) near3 (sens\$3 or detect\$3) near3 (multiple or plurality)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/09/27 13:24
L9	26	(substrate or wafer or semiconductor or workpiece) and (bubb1\$3 or foam\$3) near3 (sens\$3 or detect\$3) near3 (multiple or plurality)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/09/27 13:24
S1	10	(optical and photo and vibration) near3 (detect\$3 or sensor) and bubble	US-PGPUB; USPAT	OR	ON	2005/07/22 16:52
S2	1	(optical and photo and vibration) near3 (detect\$3 or sensor) near4 bubb1\$4 and (semiconductor or wafer)	US-PGPUB; USPAT	OR	ON	2005/07/22 16:53
S3	20	(vibration) near3 (detect\$3 or sensor) near4 bubb1\$4 and (semiconductor or wafer)	US-PGPUB; USPAT	OR	ON	2005/09/19 10:54
S4	3681	134/902,61,84,85,88,90,109-111. ccls.	US-PGPUB; USPAT	OR	ON	2005/09/19 11:10
S5	1877	S4 and (wafer or semiconductor or substrate or workpiece)	US-PGPUB; USPAT	OR	ON	2005/09/19 11:11
S6	1	S5 and (sensor or detect) near3 vibration and control\$3 and dry\$3 and (tank or vessel or bath) near3 overflow and circulat\$4	US-PGPUB; USPAT	OR	ON	2005/09/19 11:22
S7	1	S5 and (sensor or detect) near3 vibration and control\$3 and dry\$3 and (tank or vessel or bath) and overflow and circulat\$4	US-PGPUB; USPAT	OR	ON	2005/09/19 11:22
S8	1	S5 and (sensor or detect) near3 vibration and control\$3 and dry\$3 and (tank or vessel or bath) and overflow	US-PGPUB; USPAT	OR	ON	2005/09/19 11:22
S9	1	S5 and (sensor or detect) near3 vibration and control\$3 and dry\$3 and (tank or vessel or bath)	US-PGPUB; USPAT	OR	ON	2005/09/19 11:22
S10	2	S5 and (sensor or detect) near3 vibration and control\$3	US-PGPUB; USPAT	OR	ON	2005/09/19 11:22

S11	2	S5 and (sens\$3 or detect\$3) near3 vibration and control\$3	US-PGPUB; USPAT	OR	ON	2005/09/19 11:23
S12	5	S5 and (sens\$3 or detect\$3) near3 bubbl\$3 and control\$3 and vibrat\$3	US-PGPUB; USPAT	OR	ON	2005/09/19 11:43
S13	1	S5 and ((sens\$3 or detect\$3 or measur\$3) near5 bubbl\$3) and robot near3 arm	US-PGPUB; USPAT	OR	ON	2005/09/19 11:44
S14	42	((sens\$3 or detect\$3 or measur\$3) near5 bubbl\$3) and robot near3 arm	US-PGPUB; USPAT	OR	ON	2005/09/19 11:53
S15	24	((sens\$3 or detect\$3 or measur\$3) near5 bubbl\$3) and robot near3 arm and (wafer or semiconductor or substrate or workpiece)	US-PGPUB; USPAT	OR	ON	2005/09/20 15:30
S16	47	((sens\$3 or detect\$3 or measur\$3) same bubbl\$3) and robot near3 arm and (wafer or semiconductor or substrate or workpiece) and control\$4 and (dry\$3 or heat\$3)	US-PGPUB; USPAT	OR	ON	2005/09/19 13:27
S17	25	((sens\$3 or detect\$3 or measur\$3) near5 bubbl\$3) and robot near3 arm and (wafer or semiconductor or substrate or workpiece)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/09/20 15:31
S18	3139	((sens\$3 or detect\$3 or measur\$3) near5 bubbl\$3) and (wafer or semiconductor or substrate or workpiece)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/09/20 15:32
S19	51	((sens\$3 or detect\$3 or measur\$3) near5 bubbl\$3) same vibration and (wafer or semiconductor or substrate or workpiece)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/09/20 15:33
S20	50	((sens\$3 or detect\$3 or measur\$3) near5 bubbl\$3) same vibrat\$3 and (wafer or semiconductor or substrate or workpiece)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/09/20 15:33
S21	65	((sens\$3 or detect\$3 or measur\$3) near5 bubbl\$3) same vibrat\$4 and (wafer or semiconductor or substrate or workpiece)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/09/20 15:43

S22	2061	((sens\$3 or detect\$3 or measur\$3) near5 bubb1\$3) and (wafer or semiconductor or substrate or workpiece) and (dry\$3 or heat\$3 or blow\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/09/20 15:44
S23	1979	((sens\$3 or detect\$3 or measur\$3) near5 bubb1\$3) and (wafer or semiconductor or substrate or workpiece) and (dry\$3 or heat\$3 or blow\$3)	US-PGPUB; USPAT	OR	ON	2005/09/20 15:44
S24	211	((sens\$3 or detect\$3 or measur\$3) near5 bubb1\$3) and (wafer or semiconductor or substrate or workpiece) and (dry\$3 or heat\$3 or blow\$3) and arm and control\$4	US-PGPUB; USPAT	OR	ON	2005/09/22 09:48
S25	1	((sens\$3 or detect\$3 or measur\$3) near5 bubb1\$3) and (wafer or semiconductor or substrate or workpiece) and (dry\$3 or heat\$3 or blow\$3) and arm and control\$4 and transparent near3 circulat\$4	US-PGPUB; USPAT	OR	ON	2005/09/22 09:49
S26	187	((sens\$3 or detect\$3 or measur\$3) near5 bubb1\$3) and (wafer or semiconductor or substrate or workpiece) and (dry\$3 or heat\$3 or blow\$3) and arm and control\$4 and (transparent or glass or clear)	US-PGPUB; USPAT	OR	ON	2005/09/22 11:58
S27	471	((sens\$3 or detect\$3 or measur\$3) near5 bubb1\$3) and (wafer or semiconductor or substrate or workpiece) and (transparent or glass or clear) near3 (wall or container or surface or pipe or tube)	US-PGPUB; USPAT	OR	ON	2005/09/22 13:01
S28	25	((sens\$3 or detect\$3 or measur\$3) near5 bubb1\$3) and (wafer or semiconductor or substrate or workpiece).ti. and (transparent or glass or clear) near3 (wall or container or surface or pipe or tube)	US-PGPUB; USPAT	OR	ON	2005/09/22 13:44
S29	4	((sens\$3 or detect\$3 or measur\$3) near5 bubb1\$3) and (wafer or semiconductor or substrate or workpiece).ti. and (transparent or glass or clear) near3 (wall or container or surface or pipe or tube)	EPO; JPO; DERWENT	OR	ON	2005/09/22 13:24

S30	10	((sens\$3 or detect\$3 or measur\$3) near5 bubbl\$3) and (wafer or semiconductor or substrate or workpiece) and (transparent or glass or clear) near3 (wall or container or surface or pipe or tube)	EPO; JPO; DERWENT	OR	ON	2005/09/22 14:23
S31	0	((sens\$3 or detect\$3 or measur\$3) near5 bubbl\$3) and (wafer or semiconductor or substrate or workpiece) and (transparent or glass or clear) near3 ((wall or container) and (pipe or tube))	EPO; JPO; DERWENT	OR	ON	2005/09/22 13:36
S32	7	((sens\$3 or detect\$3 or measur\$3) near5 bubbl\$3) and (wafer or semiconductor or substrate or workpiece) and (transparent or glass or clear) near3 (wall or container or pipe or tube)	EPO; JPO; DERWENT	OR	ON	2005/09/22 13:37
S33	285	((sens\$3 or detect\$3 or measur\$3) near5 bubbl\$3) and (wafer or semiconductor or substrate or workpiece) and (transparent or glass or clear) near3 (wall or container or pipe or tube)	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/22 13:37
S34	11	((sens\$3 or detect\$3 or measur\$3) near5 (bubbl\$3 or foam\$3)) and (wafer or semiconductor or substrate or workpiece) and (transparent or glass or clear) near3 (wall or container or surface or pipe or tube)	EPO; JPO; DERWENT	OR	ON	2005/09/22 14:23
S35	726	((sens\$3 or detect\$3 or measur\$3) near5 (bubbl\$3 or foam\$3)) and (wafer or semiconductor or substrate or workpiece) and (transparent or glass or clear) near3 (wall or container or surface or pipe or tube)	US-PGPUB; USPAT	OR	ON	2005/09/22 14:29
S36	169	((sens\$3 or detect\$3 or measur\$3) near5 (bubbl\$3 or foam\$3)) and (wafer or semiconductor or substrate or workpiece) near3 (clean\$3 or wash\$3 or etch\$3 or treat\$4) and (transparent or glass or clear) near3 (wall or container or surface or pipe or tube)	US-PGPUB; USPAT	OR	ON	2005/09/22 14:50

S37	7	((sens\$3 or detect\$3 or measur\$3) near5 (bubbl\$3 or foam\$3)) and (wafer or semiconductor or substrate or workpiece) near3 (clean\$3 or wash\$3 or etch\$3 or treat\$4) and (transparent or clear) near3 (wall or container or pipe or tube) and arm and (dry\$3 or heat\$3)	US-PGPUB; USPAT	OR	ON	2005/09/22 16:14
S38	8	((sens\$3 or detect\$3 or measur\$3) near5 (bubbl\$3 or foam\$3)) and (wafer or semiconductor or substrate or workpiece) near3 (clean\$3 or wash\$3 or etch\$3 or treat\$4) and overflow near3 (tank or receptacle or chamber) and arm and (dry\$3 or heat\$3)	US-PGPUB; USPAT	OR	ON	2005/09/23 09:28
S39	272	((sens\$3 or detect\$3 or measur\$3) near5 (bubbl\$3 or foam\$3)) and (wafer or semiconductor or substrate or workpiece) and (tank or receptacle or chamber) and arm and (dry\$3 or heat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/09/23 09:49
S40	781	((sens\$3 or detect\$3 or measur\$3) near5 (bubbl\$3 or foam\$3)) and (wafer or semiconductor or substrate or workpiece) and (tank or receptacle or chamber) and (arm or carrier) and (dry\$3 or heat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/09/23 09:50
S41	7	((sens\$3 or detect\$3 or measur\$3) near5 (bubbl\$3 or foam\$3)) and (wafer or semiconductor or substrate or workpiece) near3 (dip\$3 or submer\$4 or immers\$4) near3 (tank or receptacle or chamber) and (arm or carrier) and (dry\$3 or heat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/09/23 10:50